

0.6Ω Quad SPST Analog Switch 4-Channel 1:1 Multiplexer – Demultiplexer

1 FEATURES

- **Bandwidth: 30MHz**
- **High Speed, Typically 50ns**
- **Supply Range: +1.8V to +5.5V**
- **Low ON-State Resistance, 0.6Ω(TYP)**
- **Break-Before-Make Switching**
- **Rail-to-Rail Operation**
- **TTL/CMOS Compatible**
- **Extended Industrial Temperature Range: -40°C to +125°C**

2 APPLICATIONS

- **Video Switching**
- **Relay Replacements**
- **USB Switching**
- **Battery-Operated Equipment**
- **Cell Phones**

3 DESCRIPTIONS

The RS2259 is a bidirectional 4-channel single-pole single-throw (SPST) analog switch, which is designed to operate from 1.8V to 5.5V.

The RS2259 device can handle both analog and digital signals. It features bandwidth (30MHz) and low on-resistance (0.6Ω TYP).

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

Device Information (1)

PART NUMBER	PACKAGE	BODY SIZE (NOM)
RS2259	TSSOP16	5.00mm×4.40mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

4 FUNCTIONAL BLOCK DIAGRAM

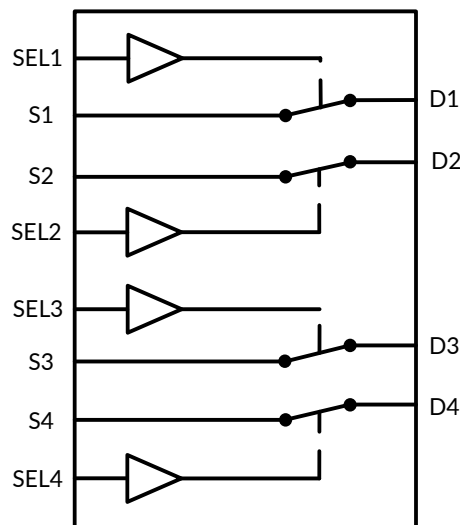


Table of Contents

1 FEATURES	1
2 APPLICATIONS	1
3 DESCRIPTIONS	1
4 FUNCTIONAL BLOCK DIAGRAM	1
5 REVISION HISTORY	3
6 PACKAGE/ORDERING INFORMATION ⁽¹⁾	4
7 PIN CONFIGURATIONS	5
7.1 Pin Description	5
7.2 Function Table	5
8 SPECIFICATIONS	6
8.1 Absolute Maximum Ratings	6
8.2 ESD Ratings	6
8.3 Recommended Operating Conditions	6
8.4 Electrical Characteristics	7
8.5 Typical Characteristics	9
9 PARAMETER MEASUREMENT INFORMATION	10
10 PACKAGE OUTLINE DIMENSIONS	13
11 TAPE AND REEL INFORMATION	14

5 REVISION HISTORY

Note: Page numbers for previous revisions may differ from page numbers in the current version.

VERSION	Change Date	Change Item
C.2.1	2024/03/07	<ol style="list-style-type: none">1. Added the TAPE AND REEL INFORMATION2. Change Thermal Information on Page 3@RevC.23. Modify packaging naming
C.3	2024/05/06	<ol style="list-style-type: none">1. Add MSL on Page 5@RevC.2.12. Add Package thermal impedance on Page 4@RevC.2.13. Update PACKAGE note

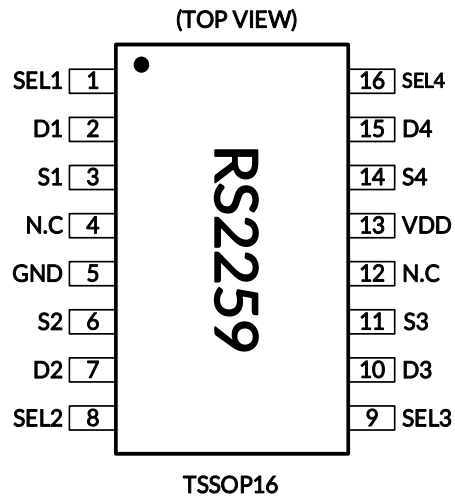
6 PACKAGE/ORDERING INFORMATION ⁽¹⁾

PRODUCT	ORDERING NUMBER	TEMPERATURE RANGE	PACKAGE LEAD	PACKAGE MARKING ⁽²⁾	MSL ⁽³⁾	PACKAGE OPTION
RS2259	RS2259XTSS16	-40°C ~125°C	TSSOP16	RS2259	MSL3	Tape and Reel, 4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.
- (3) MSL, The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications.

7 PIN CONFIGURATIONS



7.1 Pin Description

NAME	PIN	FUNCTION
	TSSOP16	
VDD	13	Power Supply
GND	5	Ground
SEL1~SEL4	1, 8, 9, 16	Logic Control Pin
D1~D4	2, 7, 10, 15	Drain pin. Can be an input or output.
S1~S4	3, 6, 11, 14	Source pin. Can be an input or output
N.C	4, 12	No internet connection

7.2 Function Table

SELx	STATE
0	All Channels ON
1	All Channels OFF

8 SPECIFICATIONS

8.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

SYMBOL	PARAMETER	MIN	MAX	UNIT
V ₊	Supply Voltage	-0.3	6	V
V _{IN}	Input Voltage (All inputs) ⁽²⁾	-0.3	(V ₊) + 0.3	
I _{IN}	Source or drain Continuous Current	-500	+500	mA
I _{PEAK}	Source or drain Peak Current	-800	+800	
θ _{JA}	Package thermal impedance ⁽³⁾	TSSOP16	45	°C/W
T _J	Junction Temperature ⁽⁴⁾	-40	150	°C
T _{stg}	Storage temperature	-65	+150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.3V beyond the supply rails should be current-limited to 10mA or less.

(3) The package thermal impedance is calculated in accordance with JESD-51.

(4) The maximum power dissipation is a function of T_{J(MAX)}, R_{θJA}, and T_A. The maximum allowable power dissipation at any ambient temperature is P_D = (T_{J(MAX)} - T_A) / R_{θJA}. All numbers apply for packages soldered directly onto a PCB.

8.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

		VALUE	UNIT	
V _(ESD)	Electrostatic discharge	Human-Body Model (HBM)	±1000	V
		Machine Model (MM)	±100	V



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

8.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

SYMBOL	PARAMETER	MIN	MAX	UNIT
V _{CC}	Supply Voltage	1.8	5.5	V
T _A	Operating temperature	-40	+125	°C

8.4 Electrical Characteristics

V₊ = 5.0 V, T_A = -40°C to 125°C (unless otherwise noted)

PARAMETER	SYMBOL	CONDITIONS	V ₊	T _A	MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
ANALOG SWITCH								
Analog Signal Range	V _S , V _D			FULL	0		V _{DD}	V
On-Resistance	R _{ON}	V _S = V ₊ /2, I _{SD} = -10mA, Switch ON, See Figure 4	5V	+25°C		0.6	1.0	Ω
				FULL			1.2	Ω
			3.3V	+25°C		1.0	1.5	Ω
				FULL			1.7	Ω
On-Resistance Match Between Channels	ΔR _{ON}	V _S = V ₊ /2, I _{SD} = -10mA, Switch ON, See Figure 4	5V	+25°C		0.04	0.1	Ω
				FULL			0.12	Ω
			3.3V	+25°C		0.04	0.1	Ω
				FULL			0.12	Ω
On-Resistance Flatness	R _{FLAT(ON)}	0 ≤ (V _S) ≤ V ₊ /2, I _{SD} = -10mA, Switch ON, See Figure 4	5V	+25°C		0.18	0.3	Ω
				FULL			0.4	Ω
			3.3V	+25°C		0.54	0.7	Ω
				FULL			0.8	Ω
Source, Drain OFF Leakage Current	I _{D(OFF)} , I _{S(OFF)}	V _D = 0.3V, V ₊ /2 V _S = V ₊ /2, 0.3V See Figure 5	1.8 to 5.5V	FULL			1	μA
Channel ON Leakage Current	I _{D(ON)} , I _{S(ON)}	V _D = 0.3V, Open V _S = Open, 0.3V See Figure 6	1.8 to 5.5V	FULL			1	μA
DIGITAL CONTROL INPUTS ⁽¹⁾								
Input High Voltage	V _{IH}		5V	FULL	1.5			V
			3.3V	FULL	1.3			V
Input Low Voltage	V _{IL}		5V	FULL			0.6	V
			3.3V	FULL			0.5	V
Input Leakage Current	I _{IN}	V _{IN} = V _{IO} or 0	1.8 to 5.5V	FULL			1	μA

(1) All unused digital inputs of the device must be held at V_{IO} or GND to ensure proper device operation.

(2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.

(3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.

Electrical Characteristics (continued)

V₊ = 5.0 V, T_A = -40°C to 125°C (unless otherwise noted)

PARAMETER	SYMBOL	CONDITIONS	V ₊	T _A	MIN	TYP	MAX	UNIT
DYNAMIC CHARACTERISTICS								
Turn-On Time	t _{ON}	V _S = V ₊ , R _L = 300Ω, C _L = 35pF, See Figure 7	5V	+25°C		50		ns
			3.3V			50		
Turn-Off Time	t _{OFF}	V _S = V ₊ , R _L = 300Ω, C _L = 35pF, See Figure 7	5V	+25°C		15		ns
			3.3V			17		
Break-Before-Make Time Delay	t _{BBM}	V _S = 3V, R _L = 300Ω, C _L = 35pF, See Figure 8	5V	+25°C		10		ns
			3.3V			11		
Off Isolation	O _{ISO}	R _L = 50Ω, Switch OFF, See Figure 10		+25°C		-68		dB
				+25°C		-86		dB
-3dB Bandwidth	BW	Switch ON, R _L = 50Ω, See Figure 9		+25°C		30		MHz
Source, Drain OFF Capacitance	C _{S(OFF)} , C _{D(OFF)}	V _S = V ₊ /2 or GND, Switch OFF		+25°C		80		pF
Source, Drain ON Capacitance	C _{S(ON)} , C _{D(ON)}	V _S = V ₊ /2 or GND, Switch ON		+25°C		350		pF
POWER REQUIREMENTS								
Power Supply Range	V _{DD}			FULL	1.8		5.5	V
Power Supply Current	I _{DD}	V _{IN} = GND or V _{DD}	5.5V	FULL			1	μA

8.5 Typical Characteristics

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

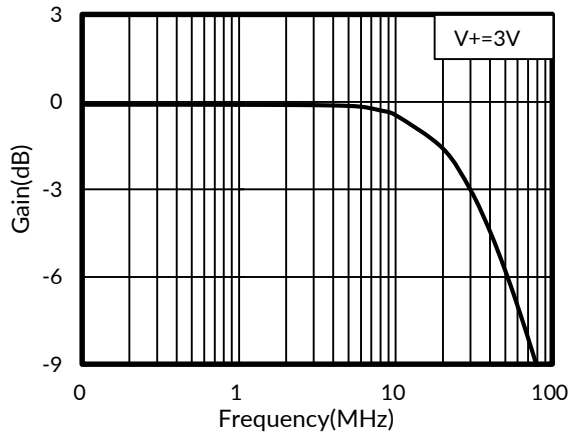


Figure 1. Bandwidth vs Frequency

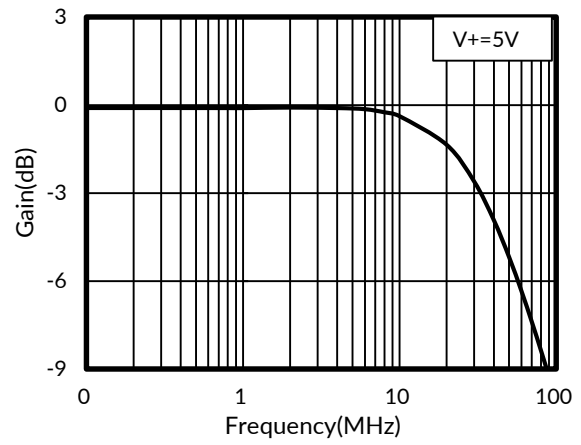


Figure 2. Bandwidth vs Frequency

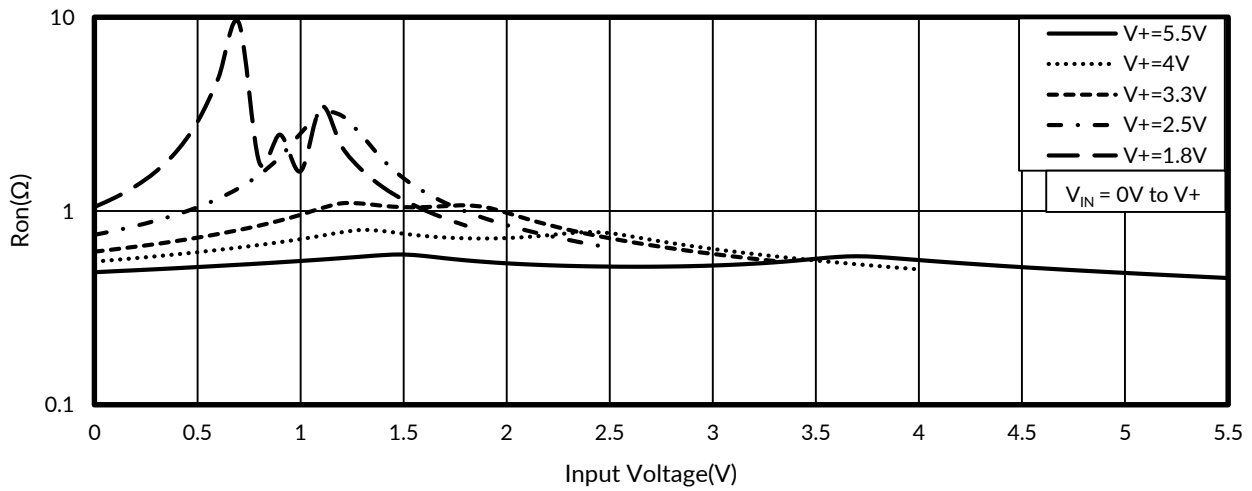


Figure 3. Typical Ron as a Function of Input Voltage

9 PARAMETER MEASUREMENT INFORMATION

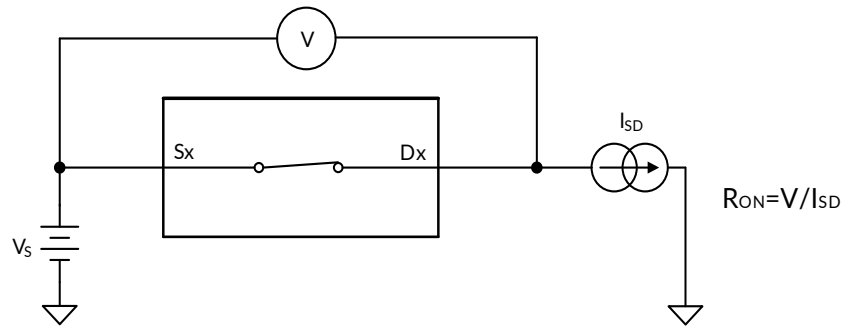


Figure 4. ON-State Resistance (R_{ON})

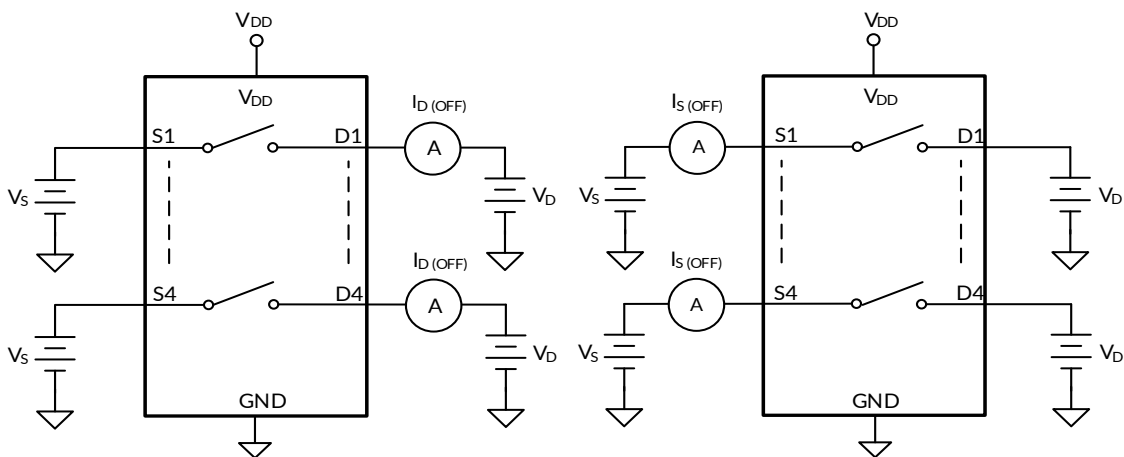


Figure 5. OFF-State Leakage Current ($I_{D(OFF)}$, $I_{S(OFF)}$)

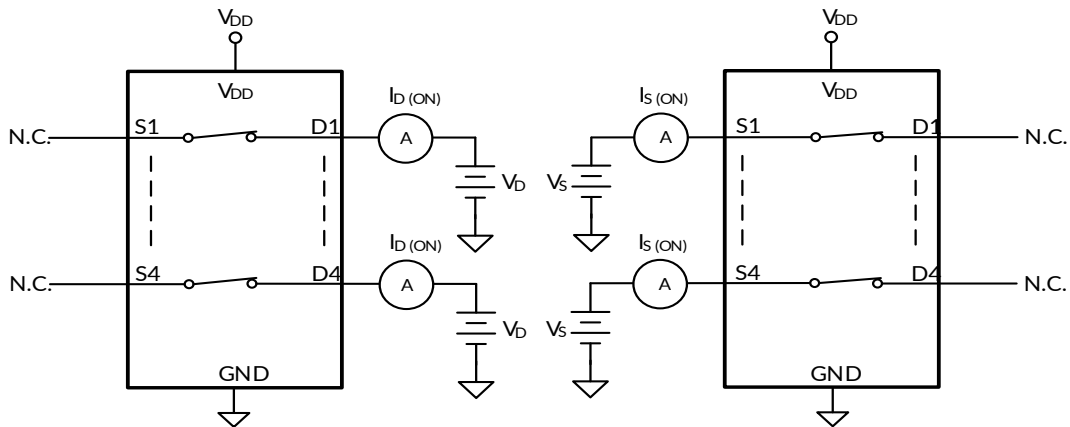


Figure 6. ON-State Leakage Current ($I_{D(ON)}$, $I_{S(ON)}$)

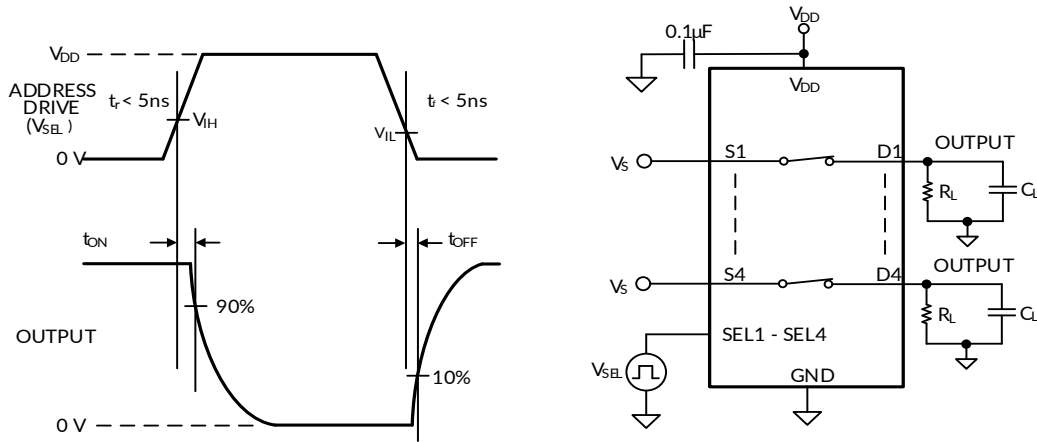


Figure 7. Turn-On (t_{ON}) and Turn-Off Time (t_{OFF})

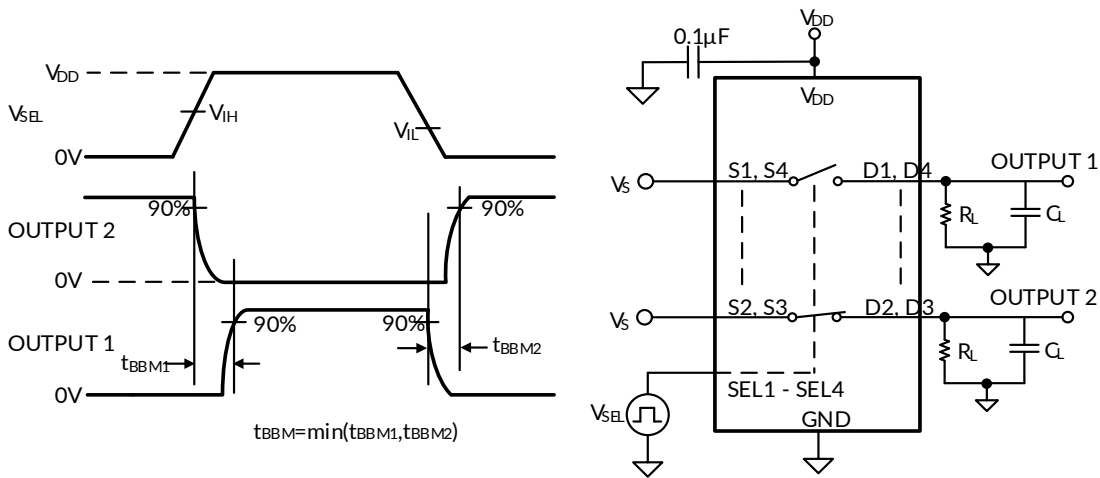


Figure 8. Break-Before-Make Time (t_{BBM})

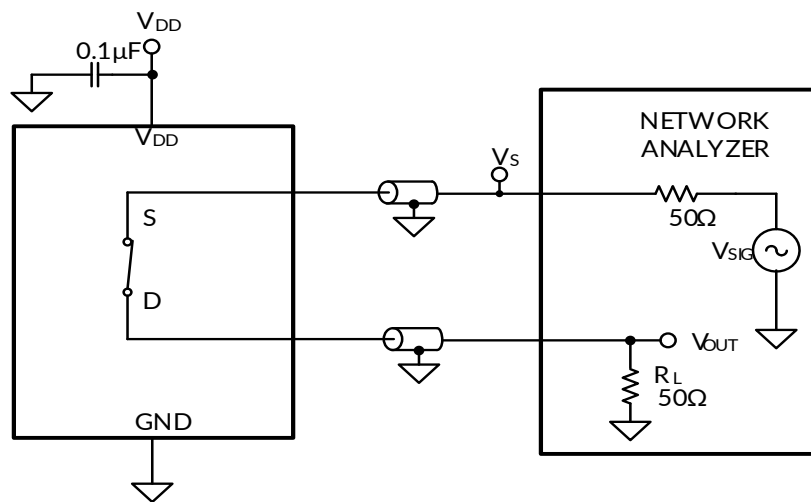


Figure 9. Bandwidth (BW)

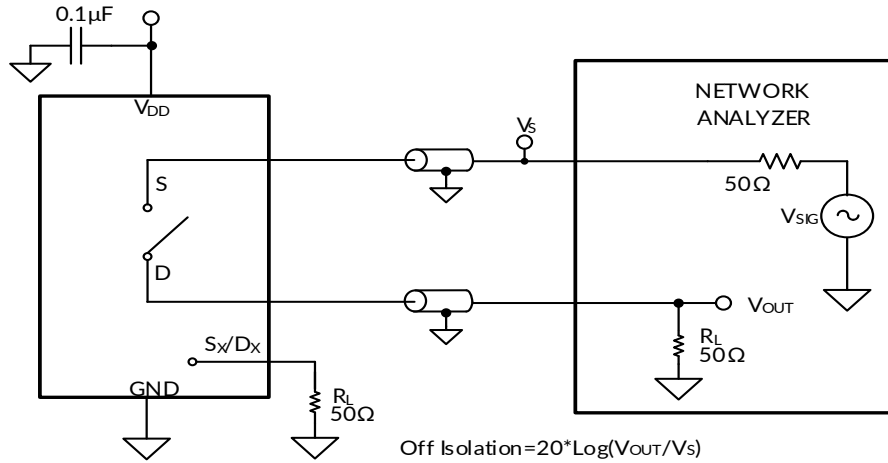


Figure 10. OFF Isolation (O_{iso})

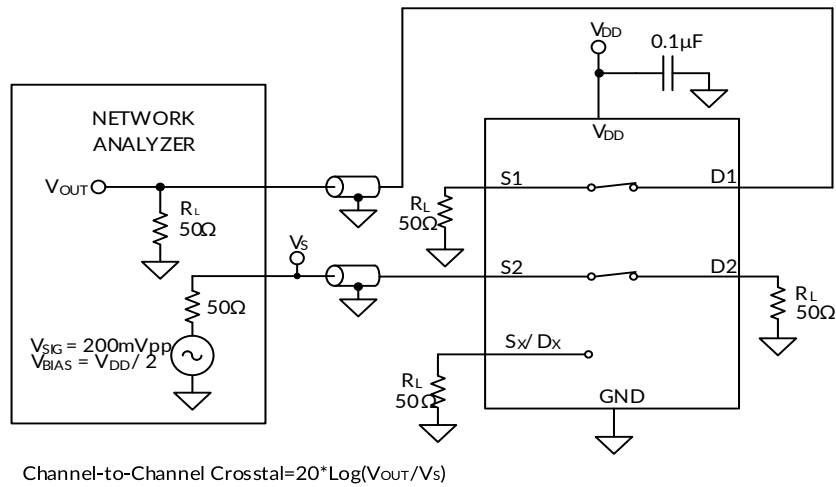


Figure 11. Crosstalk (X_{TALK})

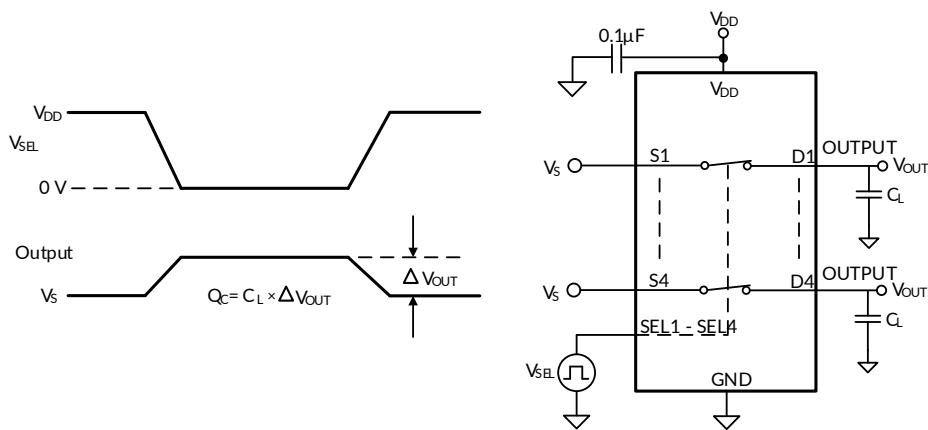
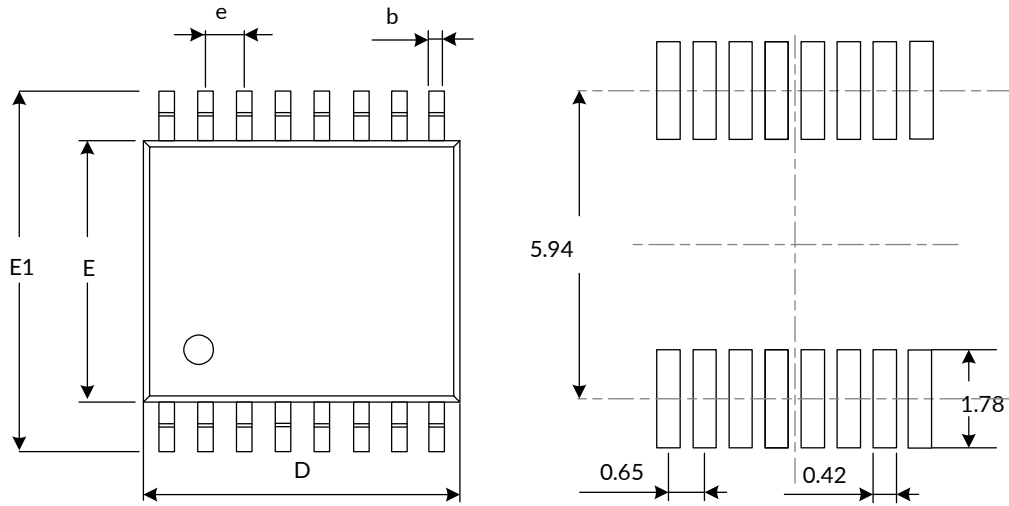
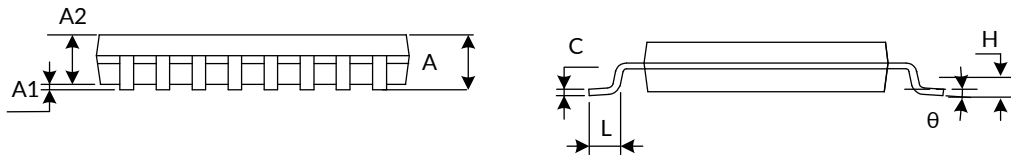


Figure 12. Charge Injection (Q_c)

10 PACKAGE OUTLINE DIMENSIONS

TSSOP16⁽³⁾


RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D ⁽¹⁾	4.860	5.100	0.191	0.201
E ⁽¹⁾	4.300	4.500	0.169	0.177
E1	6.200	6.600	0.244	0.260
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
L	0.500	0.700	0.02	0.028
H	0.250 TYP		0.010 TYP	
θ	1°	7°	1°	7°

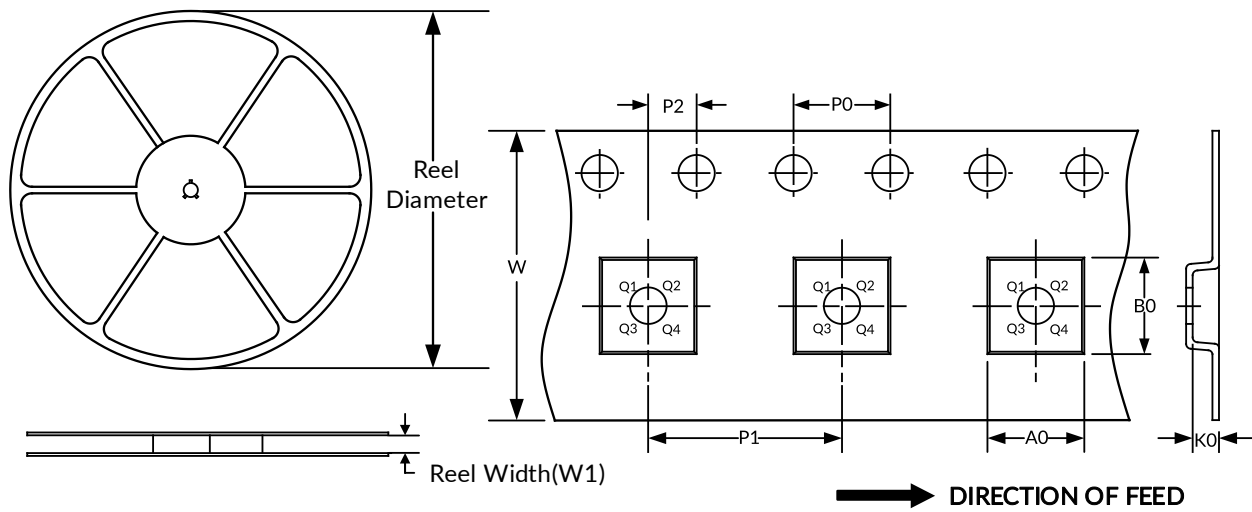
NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

11 TAPE AND REEL INFORMATION

REEL DIMENSIONS

TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width(mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
TSSOP16	13"	12.4	6.90	5.60	1.20	4.0	8.0	2.0	12.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

IMPORTANT NOTICE AND DISCLAIMER

Jiangsu Runic Technology Co., Ltd. will accurately and reliably provide technical and reliability data (including data sheets), design resources (including reference designs), application or other design advice, WEB tools, safety information and other resources, without warranty of any defect, and will not make any express or implied warranty, including but not limited to the warranty of merchantability Implied warranty that it is suitable for a specific purpose or does not infringe the intellectual property rights of any third party.

These resources are intended for skilled developers designing with Runic products You will be solely responsible for: (1) Selecting the appropriate products for your application; (2) Designing, validating and testing your application; (3) Ensuring your application meets applicable standards and any other safety, security or other requirements; (4) Runic and the Runic logo are registered trademarks of Runic Incorporated. All trademarks are the property of their respective owners; (5) For change details, review the revision history included in any revised document. The resources are subject to change without notice. Our company will not be liable for the use of this product and the infringement of patents or third-party intellectual property rights due to its use.